



Statement of Materials, Construction

20L-PDIP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.45460	Cu	7440-50-8	0.44233	31.04243	97.3
				Fe	7439-89-6	0.01068	0.74974	2.35
				Zn	7440-66-6	0.00055	0.03828	0.12
				P	7723-14-0	0.00014	0.00957	0.03
				Ag	7440-22-4	0.00091	0.06381	0.2
2	Die	Silicon Chip	0.00735	Si	7440-21-3	0.00731	0.51289	99.5
3	Die attach material	Conductive Epoxy	0.00206	Epoxy resin (5-25)	Proprietary	0.00031	0.02169	15
				Silver (70-85)	7440-22-4	0.00164	0.11494	79.5
				Aromatic Amine (1-10)	Proprietary	0.00011	0.00795	5.5
4	Wire	Gold	0.00575	Au	7440-57-5	0.00575	0.40349	99.99
5	Lead Finish	Alloy	0.0126367	Pb	7439-92-1	0.00126	0.08868	10
				Sn	7440-31-5	0.01137	0.79816	90
				Fused Silica	7631-86-9	0.63337	44.44993	67.2
6	Encapsulation	Epoxy Resin	0.942515	Epoxy resin	29690-82-2	0.18850	13.22915	20
				Phenol Resin	9003-35-4	0.07069	4.96093	7.5
				Antimony trioxide	1309-64-4	0.02828	1.98437	3
				Brominated Epoxy Resin	40039-93-8	0.01885	1.32291	2
				Carbon Black	1333-86-4	0.00283	0.19844	0.3
Total Package weight			1.42491					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%